

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S98	316	(electrochemical electroplating) and (wafer substrate workpiece semiconductor microelectronics micropiece) and anolyte and catholyte and filter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/28 11:19
S99	119	(electroplating electrowinning electrodeposit\$3) and (wafer substrate workpiece semiconductor microelectronics micropiece) and anolyte and catholyte and filter	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/28 11:30
S10 1	39	S100 not S99	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/28 11:31
S10 2	8	("3616396" "4885142" "5100517" "5256274" "5514258" "6033540" "6284108" "6540899").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/12/28 11:39
S10 3	334	(electroplating electrowinning electrodeposit\$3 plating deposit\$3) and (wafer substrate workpiece semiconductor microelectronics micropiece) and (anolyte with remov\$3 catholyte with remov\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/28 11:48
S10 4	237	S103 not (S98 S99 S100)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/28 11:57
S10 5	130	S103 not (S98 S99 S100) and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/28 11:59
S10 0	56	(electroplating electrowinning electrodeposit\$3 plating deposit\$3) and (wafer substrate workpiece semiconductor microelectronics micropiece) and (anolyte with filter\$3 catholyte with filter\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/28 12:15

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S10 8	2317	S107 and ("204" "205").clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/28 12:16
S10 9	542	S108 not (S98 S99 S100) and copper and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/28 12:17
S10 7	6073	(electroplating electrowinning electrodeposit\$3 plating deposit\$3) and (wafer substrate workpiece semiconductor microelectronics micropiece) and anode with (filter\$3 remov\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/28 12:17
S10 6	28	S103 not (S98 S99 S100) and copper and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/28 12:17
S11 0	178	(electroplating electrowinning electrodeposit\$3 plating deposit\$3) and (wafer substrate workpiece semiconductor microelectronics micropiece) and anode with (filter\$3 remov\$3) with (contaminant particulate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/28 12:18
S11 1	9	("3763027" "4062755" "4269669" "4372825" "4391694" "4431500" "4696729" "5217536" "5514258").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/12/28 12:51

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S11 2	51	("3962047" "4137867" "4170959" "4246088" "4259166" "4280882" "4304641" "4339297" "4341613" "4466864" "4469566" "4534832" "4565607" "4597836" "4696729" "4828654" "4861452" "4879007" "4906346" "4931149" "5000827" "5024746" "5078852" "5096550" "5135636" "5222310" "5227041" "5332487" "5372699" "5377708" "5391285" "5405518" "5421987" "5429733" "5437777" "5441629" "5443707" "5447615" "5462649" "5472592" "5498325" "5522975" "5597460" "5670034" "5725745" "5750014" "5776327" "5788829" "5804052" "5843296" "5855850").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/12/28 13:04
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